

Thermal Interface - Wet Dispensed

Dow Corning[®] SE4422 Thermally Conductive Adhesive

One part, gray, moisture cure thermally conductive silicone adhesive

TYPICAL PROPERTIES

Specification Writers: These values are not intended for use in preparing specifications. Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

Property	Unit	Value
Tack-Free Time at 25°C	minutes	14
Cure Time at 25°C	hrs	72
Fluidity	in mm	1.7 42
NVC (Non Volatile Content)	%	99.35
Specific Gravity (Cured)	-	2.17
Tensile Strength	psi MPa kg/cm ²	735 5.1 52
Elongation	%	130
Durometer Shore A (JIS)	-	68
Shelf Life at 25°C	months	9
Thermal Conductivity	btu/hr ft degF W/mK	0.52 0.90

DESCRIPTION

One-part RTV-cure thermally conductive materials cure with moisture exposure to produce durable, relatively low-stress elastomer with a noncorrosive by-product. Long-term, reliable protection of sensitive circuits and components is important in many of today's delicate and demanding electronic applications. With the increase in processing power and the trend toward smaller, more compact electronic modules, the need for thermal management is growing. Thermally conductive silicones function as heat transfer media, durable dielectric insulation, barriers against environmental contaminants and as stress-relieving shock and vibration absorbers over a wide temperature and humidity range. In addition to sustaining their physical and electrical properties over a broad range of operating conditions, silicones are resistant to ozone and ultraviolet degradation and have good chemical stability. Good heat transfer is dependent on a good interface between the heat producing device and the heat transfer media. Silicones have a low surface tension that enables them to wet most surfaces, which can lower the thermal contact resistance between the substrate and the material.

SUBSTRATE TESTING

To ensure maximum bond strength for adhesives on a particular substrate, 100 percent cohesive failure of the adhesive in a lap shear or similar adhesive strength test is needed. This ensures compatibility of the adhesive with the substrate being considered. Also, this test can be used to determine minimum cure time or to detect the presence of surface contaminants such as mold release agents, oils, greases and oxide films.

PROCESSING/CURING

The one-part moisture-cure adhesives are generally cured at room temperature and in a range of 0 to 80 percent relative humidity. Greater than 90 percent of their full physical

properties should be attained within 4 to 7 hours depending on the product chosen. These materials are not typically used for highly confined or deep section cures. Materials will generally cure about 0.5 inch (6.35 mm) per 7 days.

ADHESION

Dow Corning silicone adhesives are specially formulated to provide unprimed adhesion to many reactive metals, ceramics and glass, as well as to selected laminates, resins and plastics. However, good adhesion cannot be expected on non-reactive metal substrates or non-reactive plastic surfaces such as Teflon®, polyethylene or polypropylene. Special surface treatments such as chemical etching or plasma treatment can sometimes provide a reactive surface and promote adhesion to these types of substrates. Dow Corning® brand primers can be used to increase the chemical activity on difficult substrates. For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, primers should be thoroughly air dried prior to application of the silicone elastomer. Alternatively, use a low-viscosity primerless adhesive to pot your components. Poor adhesion can be experienced on plastic or rubber substrates that are highly plasticized, since the mobile plasticizers act as release agents. Small-scale laboratory evaluation of all substrates is recommended before production trials are made. In general, increasing the cure temperature and/or cure time will improve the ultimate adhesion.

USEFUL TEMPERATURE RANGES

For most uses, silicone adhesives should be operational over a temperature range of -45 to 200°C (-49 to 392 °F) for long periods of time. However, at both the low and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and

require additional considerations. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible for most products, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicones is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

SOLVENT EXPOSURE

Although highly filled silicones such as those discussed in this data sheet are generally more resistant to solvent or fuel exposure, standard silicones are intended only to survive splash or intermittent exposures. Testing should be done to confirm performance of the adhesives in the application and under the specified environmental conditions.

STORAGE AND SHELF LIFE

Shelf life is indicated by the "Use By" date found on the product label. For best results, Dow Corning thermally conductive materials should be stored at or below the maximum specified storage temperature. Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen. Any special storage and handling instructions will be printed on the product containers.

HEALTH AND ENVIRONMENTAL INFORMATION

To support Customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product

Safety and Regulatory Compliance (PS&RC) specialists available in each area. For further information, please see our website, www.dowcorning.com or consult your local Dow Corning representative.

LIMITATIONS

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

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